

# MM54HC03/MM74HC03 Quad 2-Input Open Drain NAND Gate

## **General Description**

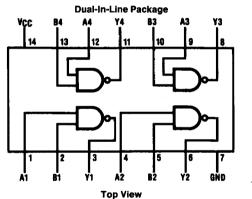
These NAND gates utilize advanced silicon-gate CMOS technology to achieve operating speeds similar to LS-TTL gates with the low power consumption of standard CMOS integrated circuits. All gates have buffered outputs. All devices have high noise immunity and the ability to drive 10 LS-TTL loads. The 54 HC/74 HC logic family is functionally as well as pin-out compatible with the standard 54 LS/74 LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{\rm CC}$  and ground.

As with standard 54HC/74HC push-pull outputs there are diodes to both  $V_{\rm CC}$  and ground. Therefore the output should not be pulled above  $V_{\rm CC}$  as it would be clamped to one diode voltage above  $V_{\rm CC}$ . This diode is added to enhance electrostatic protection.

#### **Features**

- Typical propagation delay: 12 ns
- Wide power supply range: 2-6V
- Low quiescent current: 20 µA maximum (74HC Series)
- Low input current: 1 µA maximum
- Fanout of 10 LS-TTL loads

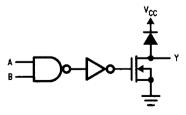
## **Connection and Logic Diagrams**



TL/F/5295-1

#### Order Number MM54HC03\* or MM74HC03\*

\*Please look into Section 8, Appendix D for availability of various package types.



TL/F/5295-2

#### Absolute Maximum Ratings (Notes 1 & 2) If Military/Aerospace specified devices are required. contact the National Semiconductor Sales Office/ Distributors for availability and specifications. Supply Voltage (V<sub>CC</sub>) -0.5 to +7.0V DC Input Voltage (VIN) -1.5 to $V_{CC} + 1.5V$ DC Output Voltage (V<sub>OUT</sub>) -0.5 to $V_{CC} + 0.5V$ Clamp Diode Current (I<sub>IK</sub>, I<sub>OK</sub>) ±20 mA DC Output Current, per pin (I<sub>OUT</sub>) ±25 mA DC V<sub>CC</sub> or GND Current, per pin (I<sub>CC</sub>) ±50 mA Storage Temperature Range (T<sub>STG</sub>) -65°C to +150°C Power Dissipation (PD) (Note 3) 600 mW S.O. Package only 500 mW

Oper	ating Conditi	ons		
		Min	Max	Units
Supply Voltage (V <sub>CC</sub> )		2	6	V
DC Input (V <sub>IN</sub> , V	or Output Voltage	0	Vcc	٧
Operatin	g Temp. Range (T₄)			
MM74HC		-40	+85	°C
MM54HC		-55	+125	°C
Input Ris	e or Fall Times			
(t <sub>r</sub> , t <sub>i</sub> )	V <sub>CC</sub> =2.0V		1000	ns
	$V_{CC} = 4.5V$		500	ns
	$V_{CC} = 6.0V$		400	ns

## DC Electrical Characteristics (Note 4)

Lead Temp. (TL) (Soldering 10 seconds)

Symbol	Parameter	Conditions	Vcc	T <sub>A</sub> =	= 25°C	74HC T <sub>A</sub> = -40 to 85°C	54HC T <sub>A</sub> = -55 to 125°C	Units
				Тур	Guaranteed Limits			
V <sub>IH</sub>	Minimum High Level Input Voltage		2.0V 4.5V 6.0V		1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V V
V <sub>IL</sub>	Maximum Low Level Input Voltage**		2.0V 4.5V 6.0V		0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V V
V <sub>OL</sub> Minimum Low Le Output Voltage	Minimum Low Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub>  I <sub>OUT</sub>   ≤ 20 μA R <sub>L</sub> = ∞	2.0V 4.5V 6.0V	0 0 0	0.† 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V V
		$V_{\text{IN}} = V_{\text{IH}}$ $ I_{\text{OUT}}  \le 4.0 \text{ mA}$ $ I_{\text{OUT}}  \le 5.2 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	0.4 0.4	>>
ILKG	Maximum High Level Output Leakage Current	V <sub>IN</sub> =V <sub>IH</sub> or V <sub>IL</sub> V <sub>OUT</sub> =V <sub>CC</sub>	6.0V		0.5	5	10	μΑ
l <sub>IN</sub>	Maximum Input Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	6.0V		±0.1	±1.0	±1.0	μА
Icc	Maximum Quiescent Supply Current	V <sub>IN</sub> =V <sub>CC</sub> or GND I <sub>OUT</sub> =0 μA	6.0V		2.0	20	40	μΑ

260°C

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C; ceramic "J" package: -12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V  $\pm$  10% the worst case output voltages ( $V_{OH}$ , and  $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC}$ = 5.5V and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

<sup>\*\*</sup>VIL limits are currently tested at 20% of V<sub>CC</sub>. The above VIL specification (30% of V<sub>CC</sub>) will be implemented no later than Q1, CY'89.

# AC Electrical Characteristics $V_{CC}=5V$ , $T_A=25^{\circ}C$ , $C_L=15$ pF, $t_f=t_f=6$ ns

Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
tpZL, tpLZ	Maximum Propagation Delay	R <sub>L</sub> =1 KΩ	10	20	ns

# **AC Electrical Characteristics**

 $V_{CC} = 2.0V$  to 6.0V,  $C_L = 50$  pF,  $t_f = t_f = 6$  ns (unless otherwise specified)

Symbol	Parameter	Conditions	Vcc	T <sub>A</sub> =25°C		74HC T <sub>A</sub> = -40 to 85°C	54HC T <sub>A</sub> = -55 to 125°C	Units	
				Тур	Guaranteed Limits				
tpLZ, tpZL	Maximum Propagation Delay	R <sub>L</sub> =1 KΩ	2.0V 4.5V 6.0V	63 13 11	125 25 21	158 32 27	186 37 32	ns ns ns	
t <sub>THL</sub>	Maximum Output Fall Time		2.0V 4.5V 6.0V	30 8 7	75 15 13	95 19 16	110 22 19	ns ns ns	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	(per gate)		20				pF	
C <sub>IN</sub>	Maximum Input Capacitance			5	10	10	10	pF	

Note 5:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$ . The power dissipated by  $R_L$  is not included.